

EMI8041, EMI8042, EMI8043

Product Preview

Common Mode Filter with ESD Protection

Functional Description

The EMI804x is a family of Common Mode Filters (CMF) with integrated ESD protection, a first in the industry. Differential signaling I/Os can now have both common mode filtering and ESD protection in one package. The EMI804x protects against ESD pulses up to ± 15 kV contact per the IEC61000-4-2 standard.

The EMI804x is well-suited for protecting systems using high-speed differential ports such as USB 3.0, HDMI 1.3/1.4/2.0; corresponding ports in removable storage and other applications.

The EMI804x is available in a RoHS-compliant, XDFN6 for 1 Differential Pair, XDFN10 for 2 Differential Pair and XDFN16 package for 3 Differential Pair.

Features

- Total Insertion Loss $DM_{LOSS} < 2.5$ dB at 2.5 GHz
- Large Differential Mode Cutoff Frequency $f_{3dB} > 5$ GHz
- High Common Mode Stop Band Attenuation:
15 dB at 700 MHz, 30 dB at 2.4 GHz
- Low Channel Resistance 6.0 Ω
- Provides ESD Protection to IEC61000-4-2 Level 4, ± 15 kV Contact
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- USB 3.0
- HDMI 1.3/1.4/2.0
- MHL 2.0
- eSATA

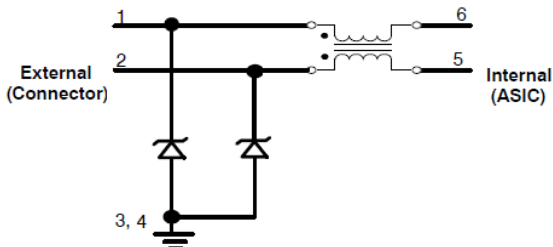


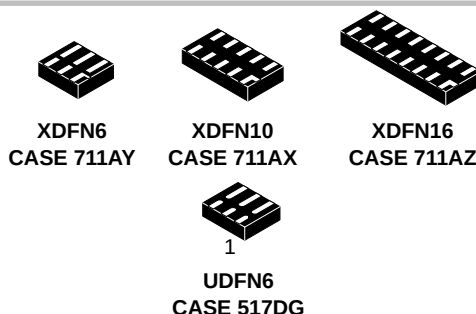
Figure 1. EMI8041 Electrical Schematic

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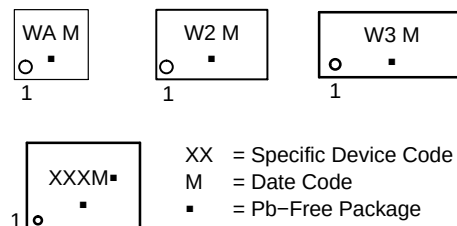


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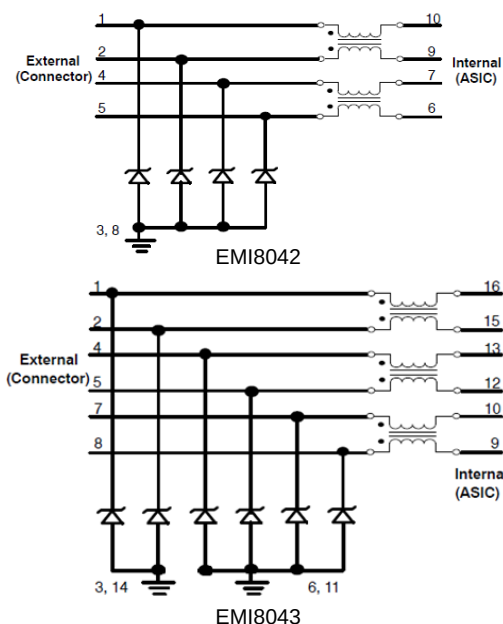
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MARKING DIAGRAMS



ELECTRICAL SCHEMATICS



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

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PIN FUNCTION DESCRIPTION

Pin Name	Device Pin			Type	Description
	EMI8041	EMI8042	EMI8043		
In_1+	1	1	1	I/O	CMF Channel 1+ to Connector (External)
In_1-	2	2	2	I/O	CMF Channel 1- to Connector (External)
Out_1+	6	10	16	I/O	CMF Channel 1+ to ASIC (Internal)
Out_1-	5	9	15	I/O	CMF Channel 1- to ASIC (Internal)
In_2+	NA	4	4	I/O	CMF Channel 2+ to Connector (External)
In_2-	NA	5	5	I/O	CMF Channel 2- to Connector (External)
Out_2+	NA	7	13	I/O	CMF Channel 2+ to ASIC (Internal)
Out_2-	NA	6	12	I/O	CMF Channel 2- to ASIC (Internal)
In_3+	NA	NA	7	I/O	CMF Channel 3+ to Connector (External)
In_3-	NA	NA	8	I/O	CMF Channel 3- to Connector (External)
Out_3+	NA	NA	10	I/O	CMF Channel 3+ to ASIC (Internal)
Out_3-	NA	NA	9	I/O	CMF Channel 3- to ASIC (Internal)
VN	3,4	3, 8	3,6,14,11	GND	Ground

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Operating Temperature Range	T _{OP}	-40 to +85	°C
Storage Temperature Range	T _{STG}	-65 to +150	°C
Maximum Lead Temperature for Soldering Purposes (1/8" from Case for 10 seconds)	T _L	260	°C
DC Current per Line	I _{LINE}	100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

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ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V _{RWM}	Reverse Working Voltage	(Note 3)		3.3		V
V _{BR}	Breakdown Voltage	I _T = 1 mA; (Note 4)	4.0		9.0	V
I _{LEAK}	Channel Leakage Current	T _A = 25°C, V _{IN} = 3.3 V, GND = 0 V			1.0	μA
R _{CH}	Channel Resistance (Pins 1–6, 2–5) – EMI8041 (Pins 1–10, 2–9, 4–7 and 5–6) – EMI8042 (Pins 1–16, 2–15, 4–13, 5–12, 7–10 and 8–9) – EMI8043			6.0		Ω
DM _{LOSS}	Differential Mode Insertion Loss	@ 2.5 GHz		2.5		dB
f _{3dB}	Differential Mode Cut-off Frequency	50 Ω Source and Load Termination		5.0		GHz
F _{atten}	Common Mode Stop Band Attenuation	@ 700 MHz		15		dB
V _{ESD}	In-system ESD Withstand Voltage a) Contact discharge per IEC 61000-4-2 standard, Level 4 (External Pins) b) Contact discharge per IEC 61000-4-2 standard, Level 1 (Internal Pins)	(Notes 1 and 2)	±15 ±2			kV
V _{CL}	TLP Clamping Voltage	Forward I _{PP} = 8 A Forward I _{PP} = 16 A Forward I _{PP} = –8 A Forward I _{PP} = –16 A		7.26 11.8 –3.5 –6.7		V

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Standard IEC61000–4–2 with C_{Discharge} = 150 pF, R_{Discharge} = 330, GND grounded.
2. These measurements performed with no external capacitor.
3. TVS devices are normally selected according to the working peak reverse voltage (V_{RWM}), which should be equal to or greater than the DC or continuous peak operating voltage level.
4. V_{BR} is measured at pulse test current I_T.

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TYPICAL CHARACTERISTICS

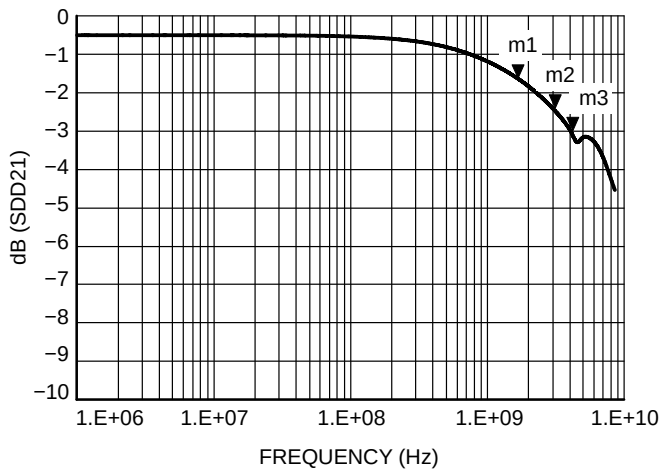


Figure 2. Typical Differential Mode Attenuation vs. Frequency

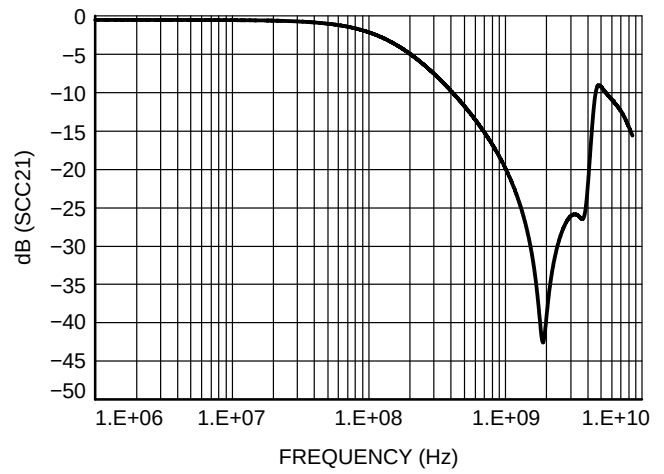


Figure 3. Typical Common Mode Attenuation vs. Frequency

Interface	Data Rate (Gb/s)	Fundamental Frequency (GHz)	EMI804x Insertion Loss (dB)
HDMI 1.3/1.4	3.4	1.7 (m1)	m1 = 1.65
USB 3.0	5.0	2.5 (m2)	m2 = 2.13
HDMI 2.0	6.0	3.0 (m3)	m3 = 2.41

TRANSMISSION LINE PULSE (TLP) MEASUREMENTS

Transmission Line Pulse (TLP) provides current versus voltage (I-V) curves in which each data point is obtained from a 100 ns long rectangular pulse from a charged transmission line. A simplified schematic of a typical TLP system is shown in Figure 4. TLP I-V curves of ESD protection devices accurately demonstrate the product's ESD capability because the 10 s of amps current levels and under 100 ns time scale match those of an ESD event. This is illustrated in Figure 5 where an 8 kV IEC61000-4-2 current waveform is compared with TLP current pulses at 8 A and 16 A. A TLP curve shows the voltage at which the device turns on as well as how well the device clamps voltage over a range of current levels. Typical TLP I-V curves for the EMI804x are shown in Figure 4.

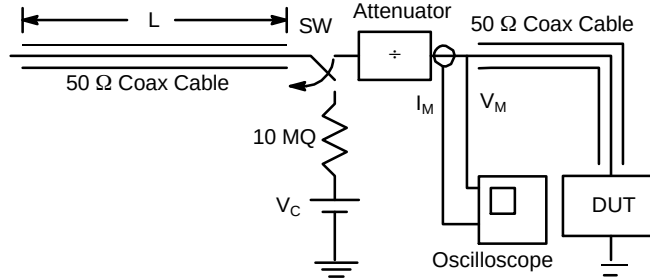


Figure 4. Simplified Schematic of a Typical TLP System

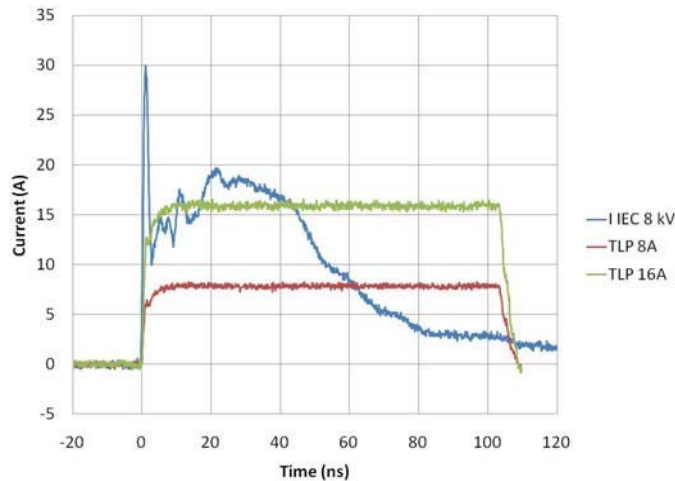


Figure 5. Comparison Between 8 kV IEC61000-4-2 and 8 A and 16 A TLP Waveforms

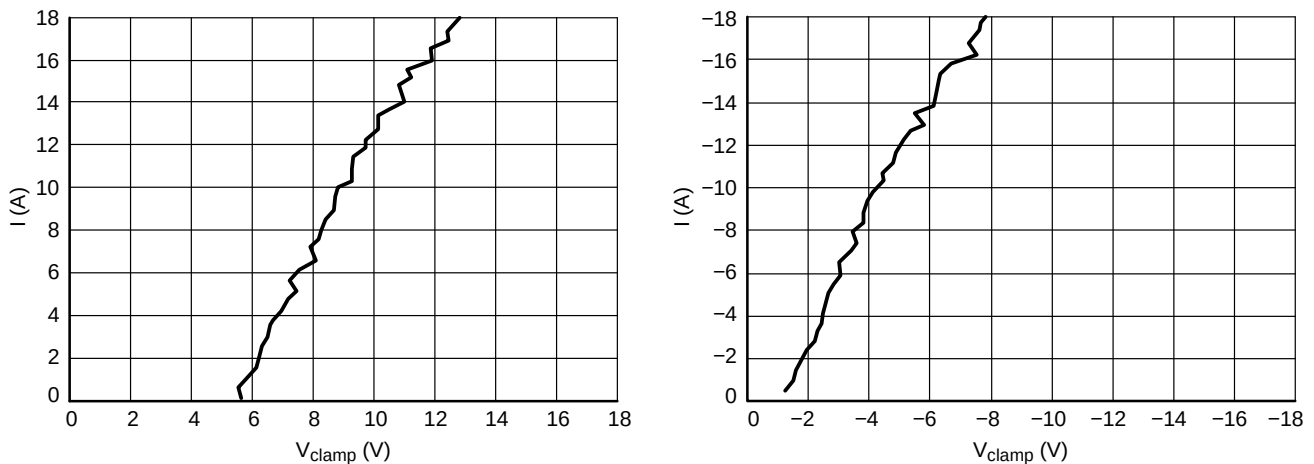


Figure 6. Positive and Negative TLP Waveforms

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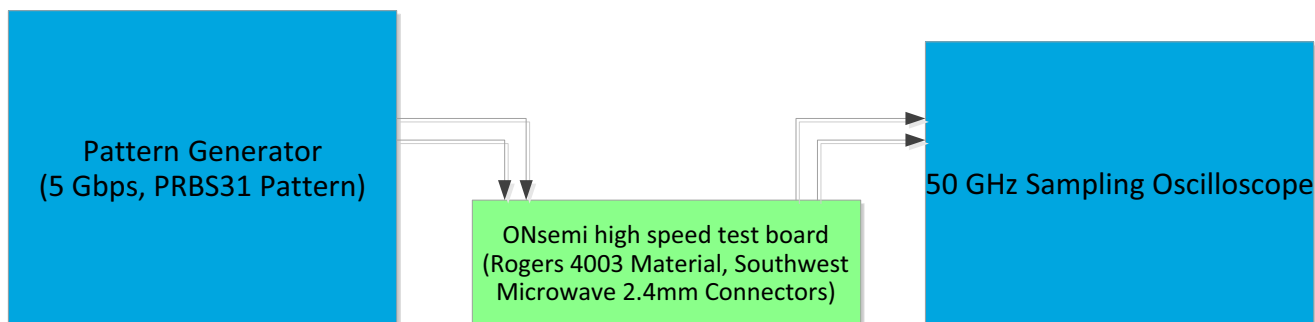


Figure 7. Eye Diagram Test Setup for 5Gbps Data Rate

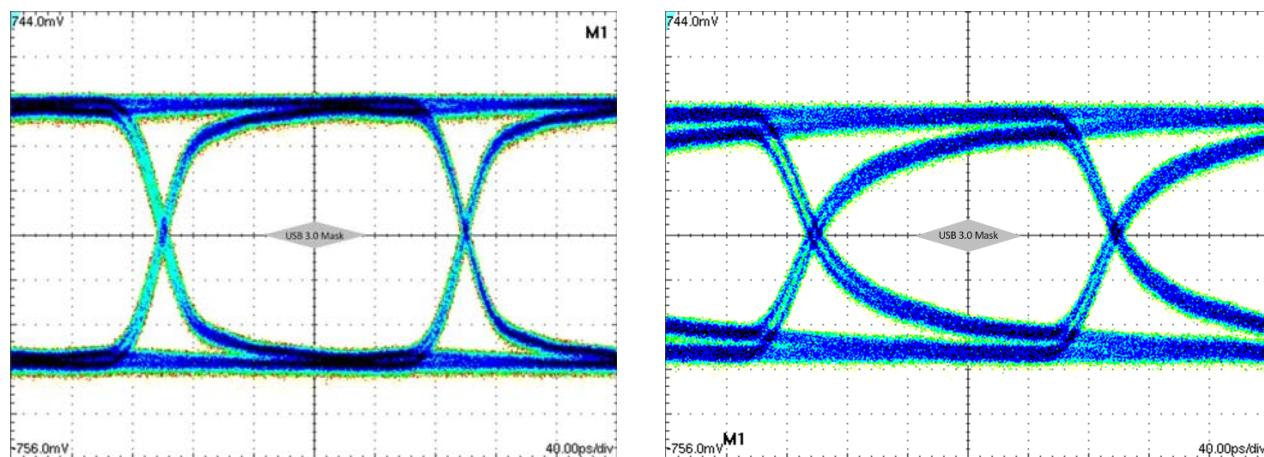


Figure 8. Eye Diagram 5Gbps with and without EMI804x

	Eye Height (mVppd)	Rise Time (ps)	Fall Time (ps)	Jrms (ps)	Jpp (ps)
Reference (No Device)-Left Figure	724	30.4	29.6	1.997	9.6
EMI804x Right Figure	405	60	60.8	3.484	16

ORDERING INFORMATION

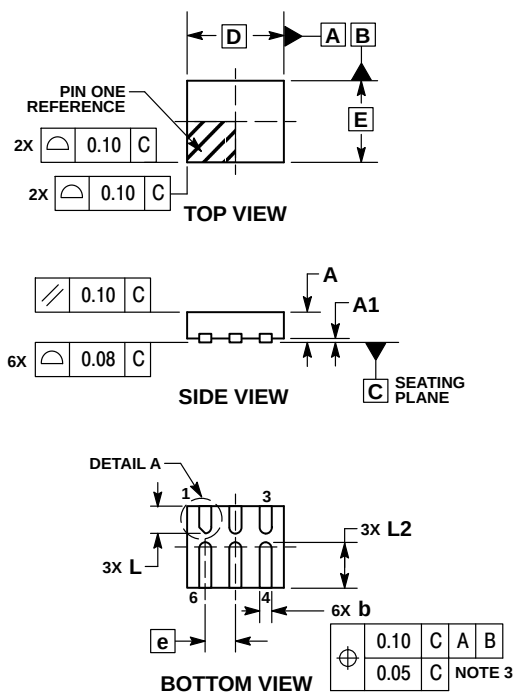
Orderable Part Number	Package	Shipping
EMI8041MUTAG	XDFN6 (Pb-Free)	3000 / Tape & Reel
EMI8042MUTAG	XDFN10 (Pb-Free)	3000 / Tape & Reel
EMI8043MUTAG	XDFN16 (Pb-Free)	3000 / Tape & Reel
EMI8041BMUTAG	UDFN6 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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PACKAGE DIMENSIONS

UDFN6 1.6x1.35, 0.5P
CASE 517DG
ISSUE O

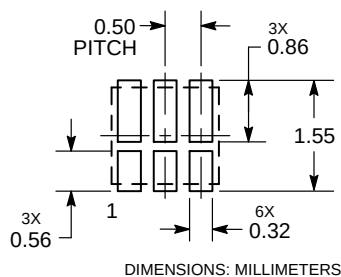


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
b	0.15	0.25
D	1.60 BSC	
E	1.35 BSC	
e	0.50 BSC	
L	0.35	0.55
L2	0.65	0.85

RECOMMENDED MOUNTING FOOTPRINT

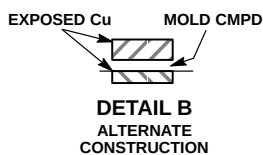
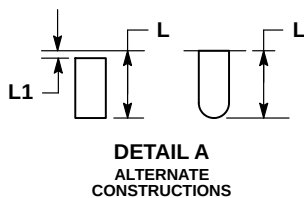
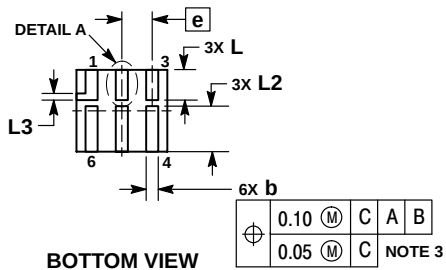
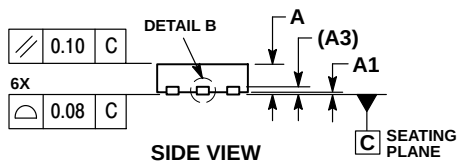
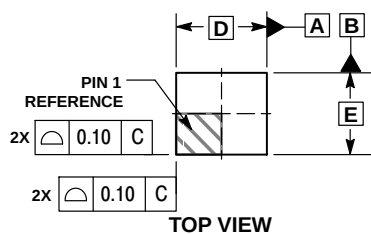


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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PACKAGE DIMENSIONS

XDFN6, 1.50x1.35, 0.5P
CASE 711AY
ISSUE O

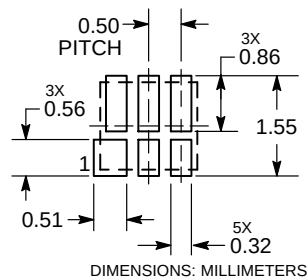


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2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSIONS b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.

DIM	MILLIMETERS	
	MIN	MAX
A	0.40	0.50
A1	0.00	0.05
A3	0.15	REF
b	0.15	0.25
D	1.50	BSC
E	1.35	BSC
e	0.50	BSC
L	0.35	0.55
L1	---	0.15
L2	0.65	0.85
L3	0.15	REF

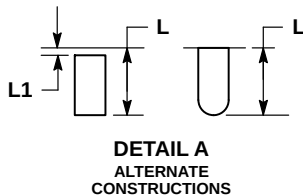
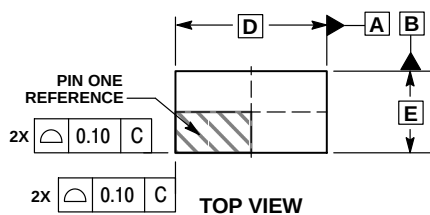
RECOMMENDED MOUNTING FOOTPRINT



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PACKAGE DIMENSIONS

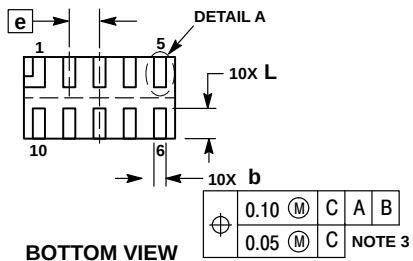
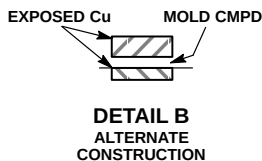
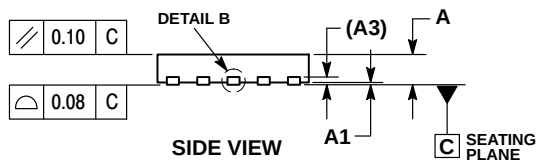
XDFN10 2.50x1.35, 0.5P
CASE 711AX
ISSUE O



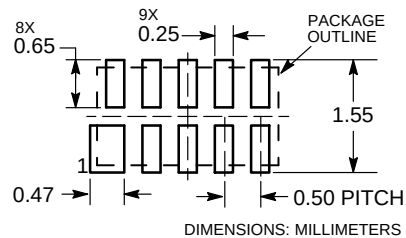
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DIM	MILLIMETERS	
	MIN	MAX
A	0.40	0.50
A1	0.00	0.05
A3	0.15 REF	
b	0.15	0.25
D	2.50 BSC	
E	1.35 BSC	
e	0.50 BSC	
L	0.40	0.60
L1	---	0.15



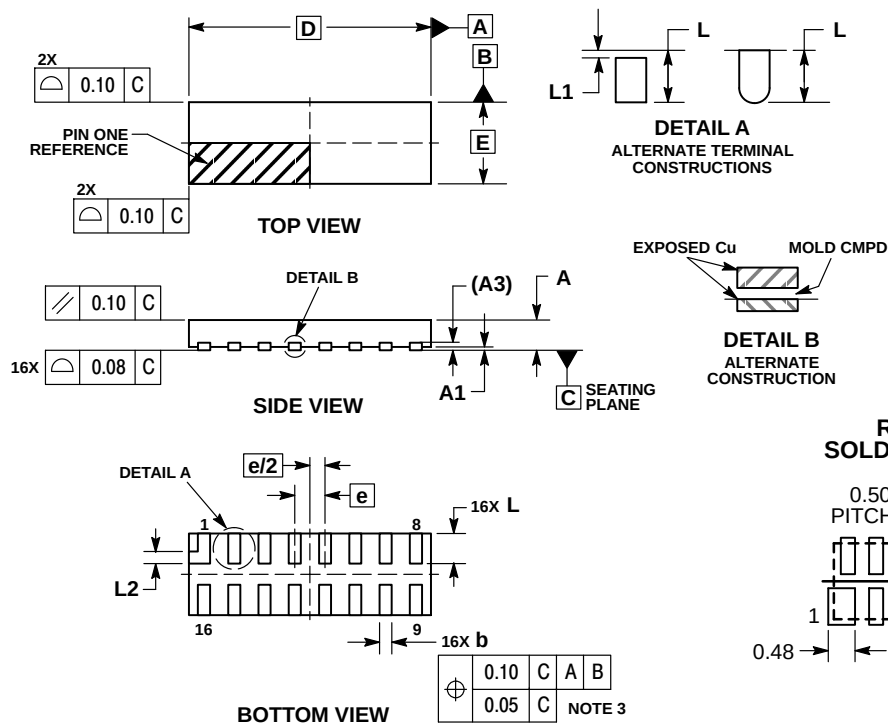
RECOMMENDED MOUNTING FOOTPRINT



EMI8041, EMI8042, EMI8043

PACKAGE DIMENSIONS

XDFN16 4.0x1.35, 0.5P CASE 711AZ ISSUE O



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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